

LOCAL CONTROL OF UNDERFILL FLOW ON HIGH DENSITY PACKAGES,  
PACKAGES AND SYSTEMS MADE THEREWITH,  
AND METHODS OF MAKING SAME

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ABSTRACT OF THE DISCLOSURE

An article includes a mounting substrate, a passive component site on the mounting substrate, and an active component site on the mounting substrate. The article also includes a fluid flow barrier disposed local to the passive component site  
10 and spaced apart from the active component site. The fluid flow barrier can be a recess that resists fluid flow thereinto because of surface tension of the fluid when it meets the recess edge. The fluid flow barrier can include a boundary that diverts fluid flow due to the angle of the recess edge as the fluid approaches it. An embodiment also includes a packaging system that includes the article and at least  
15 one passive component. An embodiment also includes a method of assembling the article or the packaging system.

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